

KOH Etching System (Model:ETC-8001CE)

Features

The molten KOH etching is a useful method for revealing the etch pits of SiC wafer or GaN wafer.

This system is capable of KOH etching process safely and automatically.



Specifications

MODEL	ETC-8001CE
Crucible size	φ250×H190(t2)
Wafer size	1×8"φ
Maximum heating temperature	700°C
Temp. control stability	±1°C
Wafer holder lift	auto
Wafer holder rotation	max 10rpm
Crucible shutter	auto
Power Supply	1φ200V 40A
Exhaust port diameter	φ100
System size	W1550×D950×H1700
System weight	500kg